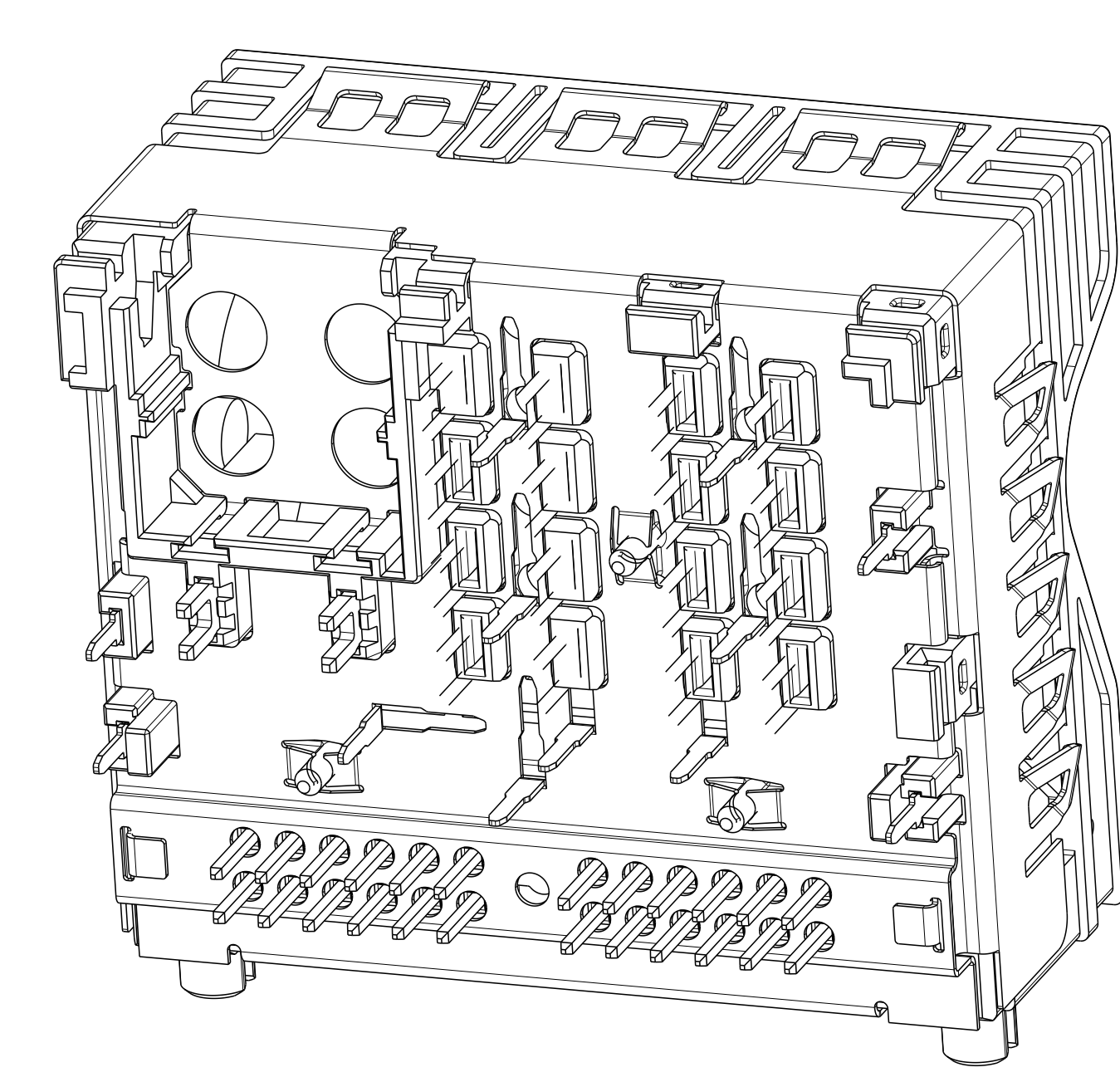
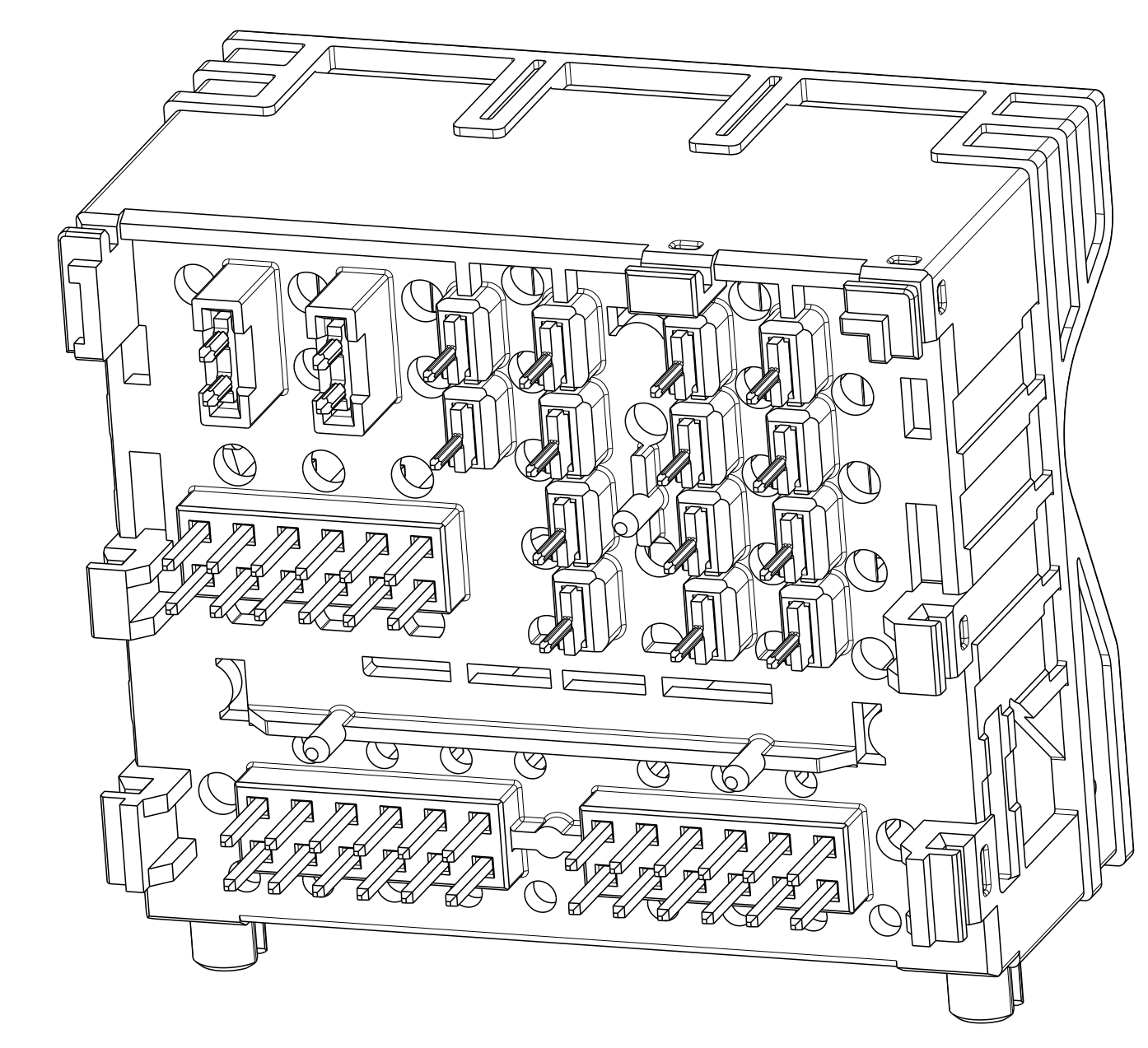
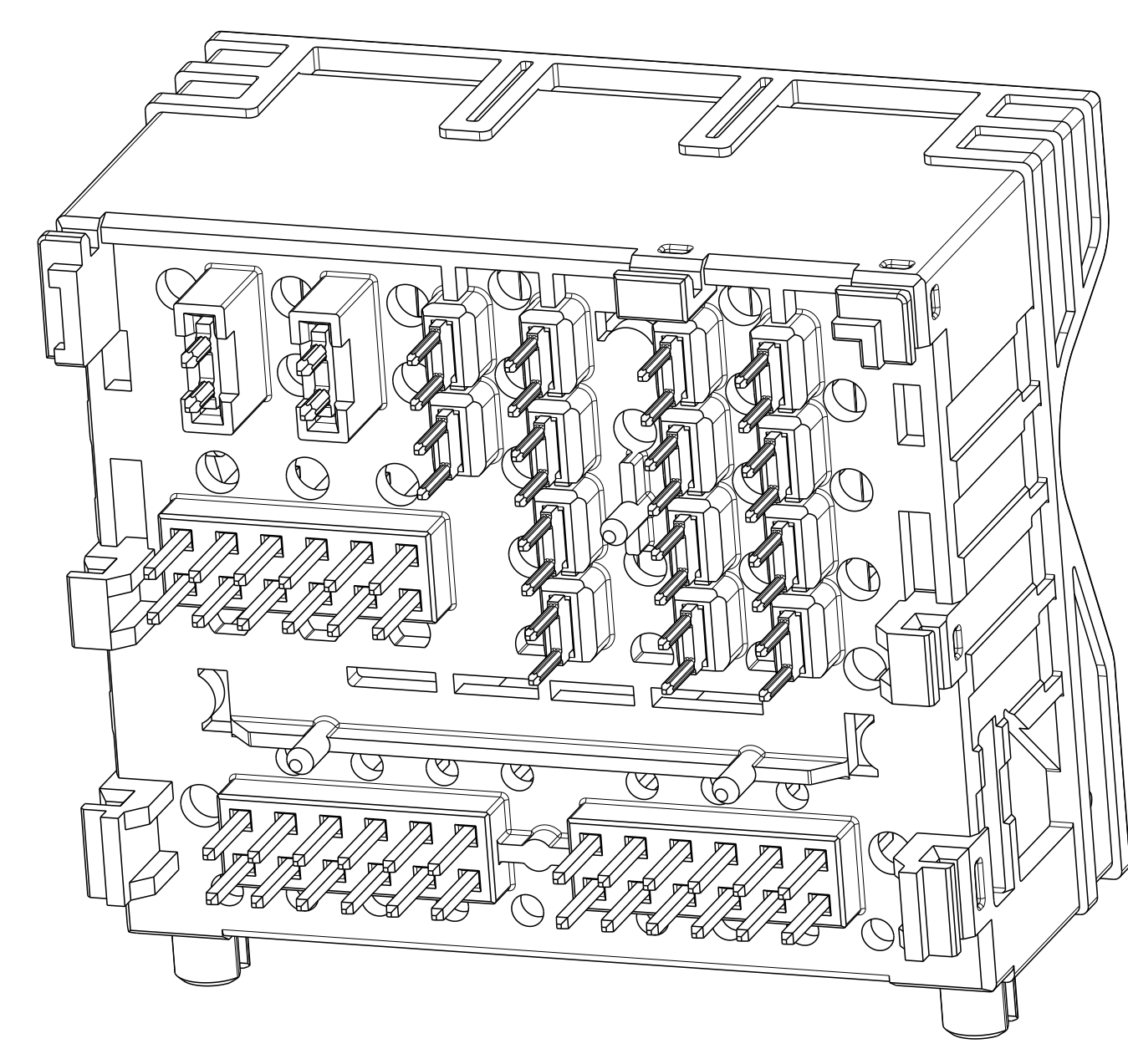
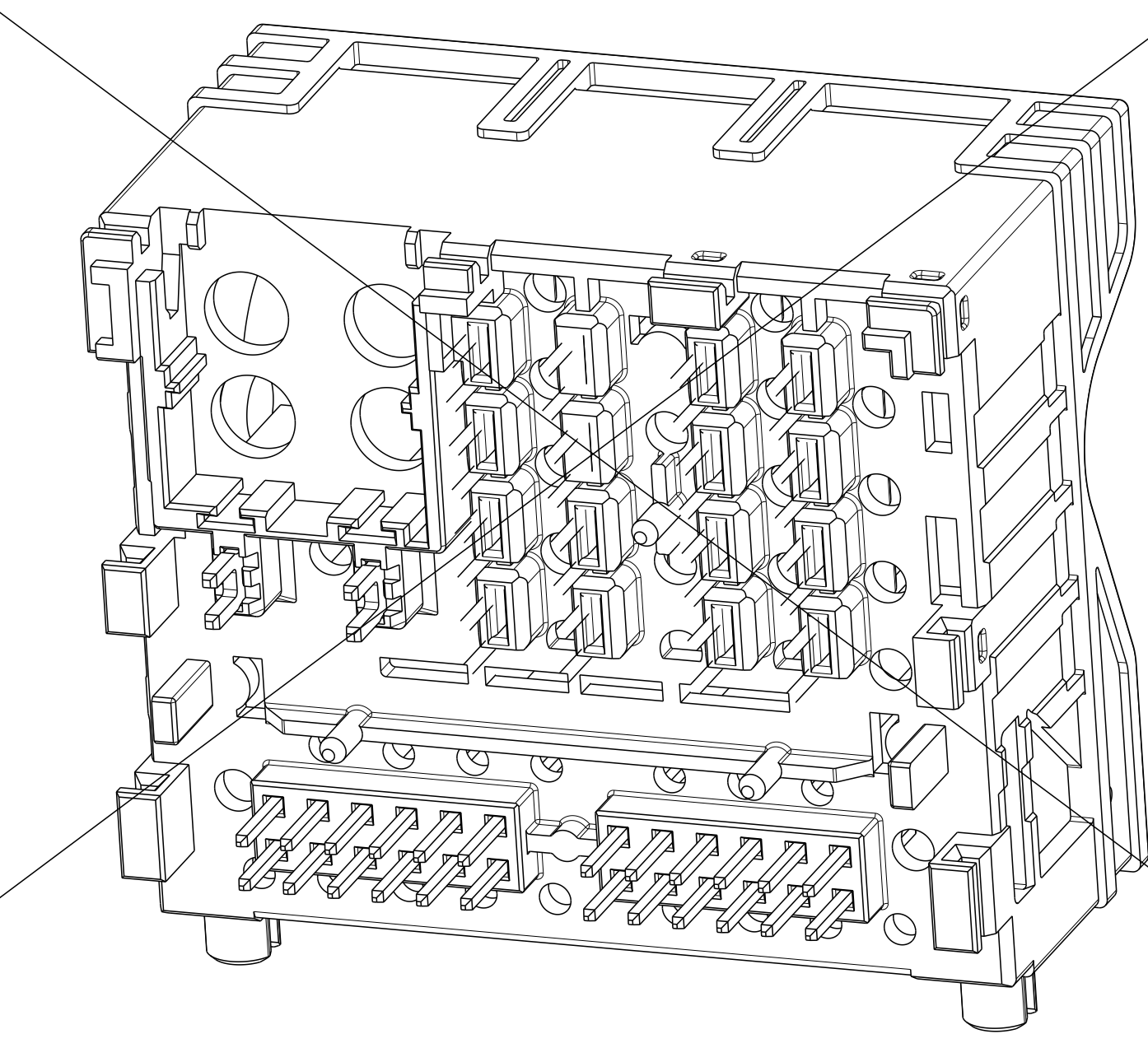
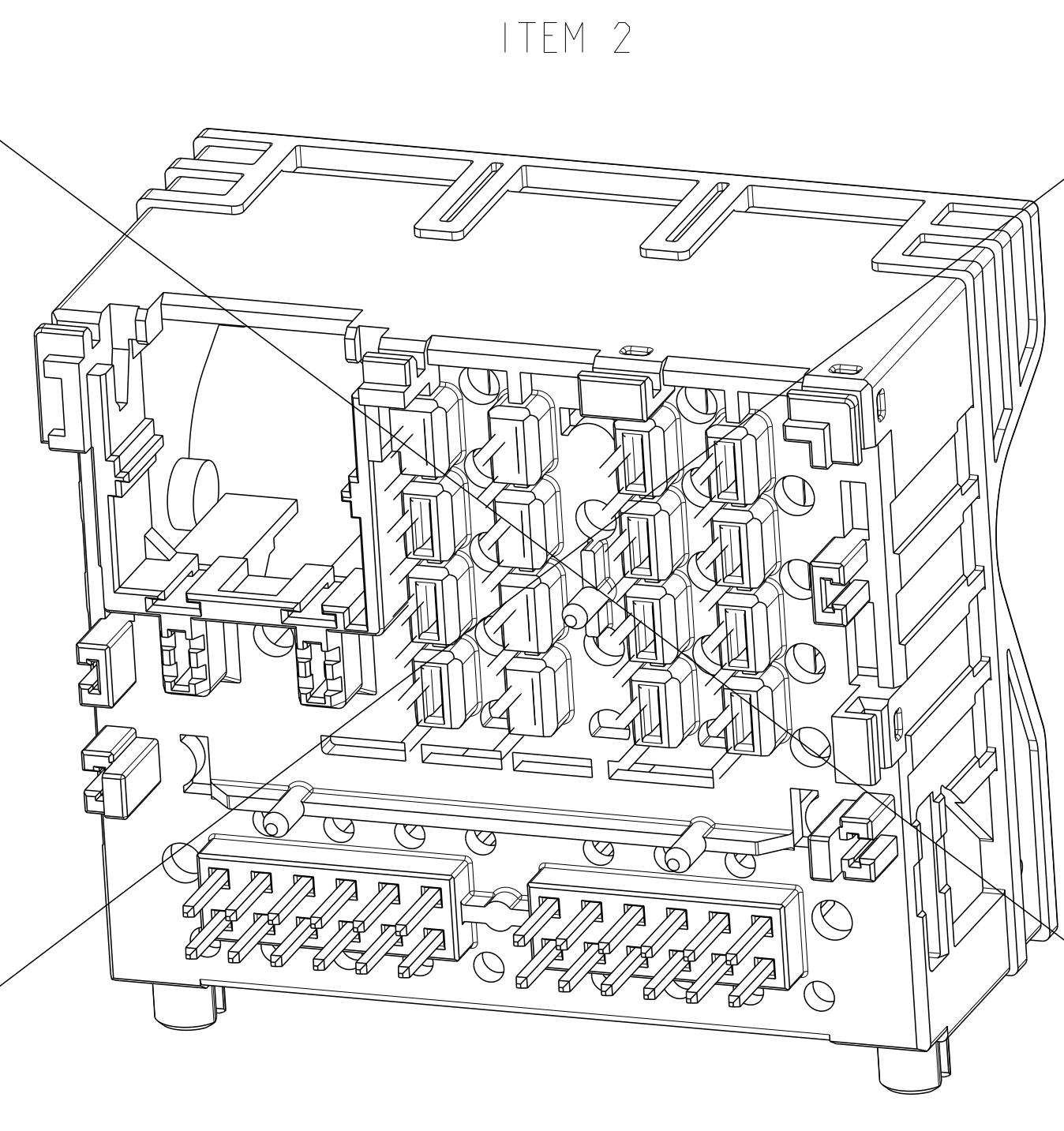
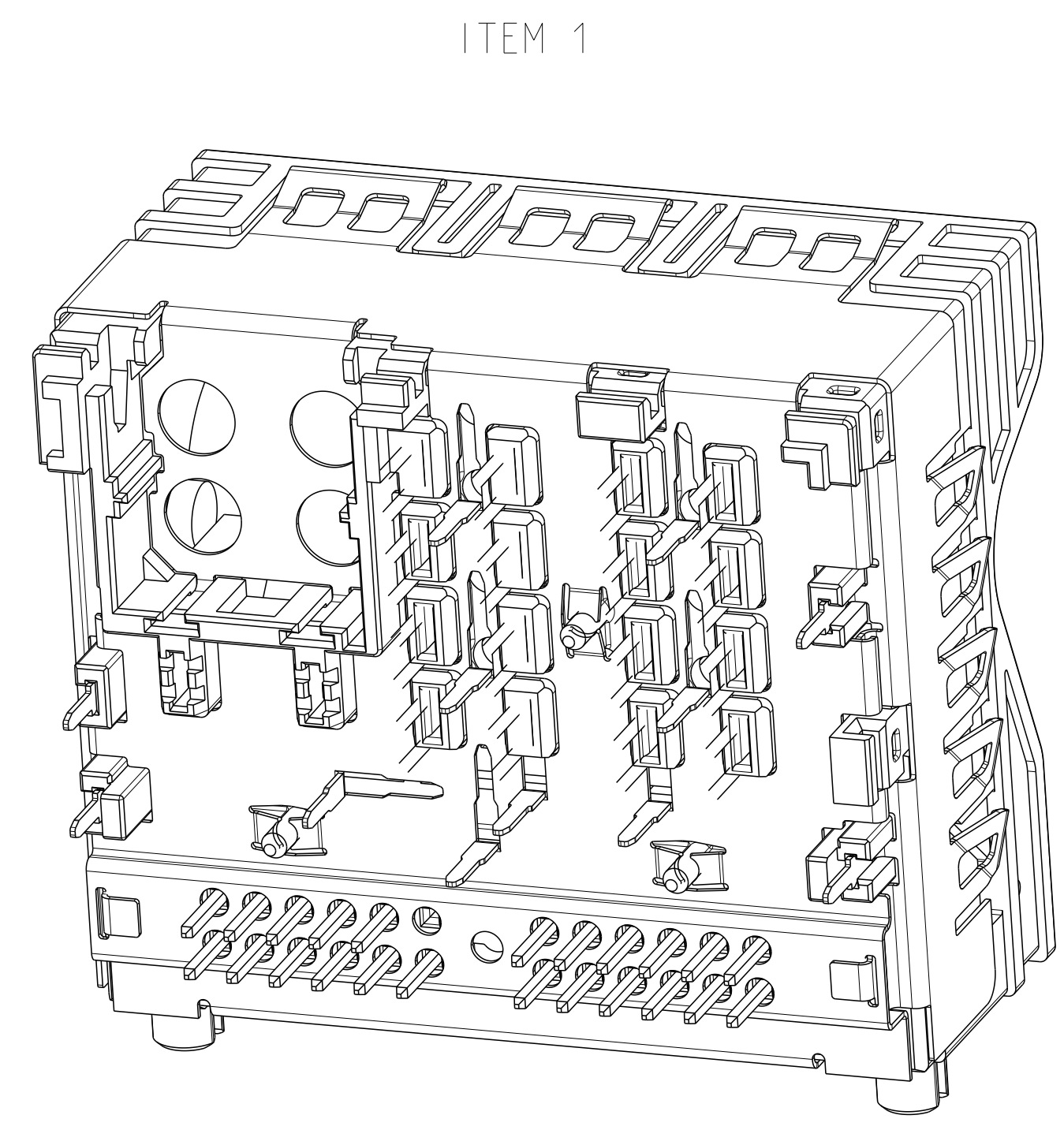


REVOLUTIONS		DATE	BY	APPD
C1	PROPOSAL ITEM 6	28AUG2015	MM	BF
D	ECR-15-015465	21OCT2015	MM	BF
D1	ECR-21-003660	29MAY2021	KG	MM
D2	ECR-23-168604	19FEB2024	KG	MM



Bemerkungen  
NOTES

- 1 Fehlende Masse siehe 3D-Modell, Rev A  
MISSING DIMENSION SEE 3D MODEL, REV. A
- 2 Kontaktausdrueckkraft mit Vorschub 25mm/min  
(nach Schnittstelle, Bemerkung 8)  
PRESS OUT FORCE OF CONTACTS WITH FORCE 25mm/min  
(ACC. INTERFACE, NOTE 8)  
PIN (0.63x0.63) >=25N  
TAB (2.8x0.6) >=60N
- 3 Verpackung: siehe Spezifikation V2208016  
PACKING: SEE SPECIFICATION V2208016
- 4 Loetbarkeit gemass DIN IEC 68-2-20, Alterung 3  
SOLDERABILITY ACCORDING DIN IEC 68-2-20, AGEING 3
- 5 Im Loetbereich blanke Stanzkanten zulaessig  
AT SOLDER SIDE BLANK CUTTING EDGES PERMITTED
- 6 Material: PCT-GF30, schwarz  
MATERIAL: PCT-GF30, BLACK
- 7 Schnittstellenverantwortung liegt bei Fa. TE Connectivity  
INTERFACE RESPONSIBILITY IS AT TE CONNECTIVITY
- 8 TE Schnittstelle nach C-114-18063-81 Rev. C4 fuer 40 polig  
TE INTERFACE ACC TO C-114-18063-81 REV. C4 for 40 POS.  
  
TE Schnittstelle nach C-114-18949 Rev. A1 fuer 52 polig  
TE INTERFACE ACC TO C-114-18949 REV. A1 for 52 POS.
- 9 Schnittstelle ist nicht Bestandteil des PPAP  
INTERFACE IS NOT PART OF PPAP
- 10 Im Loetbereich blanke Stanzkanten nicht zulaessig  
AT SOLDER SIDE BLANK CUTTING EDGES NOT PERMITTED
- 11 TE Pruefsymbol nach TE Spezifikation  
TE SPECIFIC CHARACTERISTIC ACC. TE SPECIFICATION
- 12 Fuer den Gegenstecker wird die Verwendung von Kontakten  
nach Zeichnung 1534616 empfohlen  
FOR THE COUNTERPART IS RECOMMENDED TO USE THE CONTACT  
ACC. DRWG 1534616
- 13 Messanweisung nach 108-94370 (40 pol.) und 108-94377 (52 pos.)  
MEASURING INSTRUCTION PER 108-94370 (40 pos.) and 108-94377 (52 pos.)
- 14  $\begin{matrix} \text{Ø} 0.5 \text{ (M)} \\ \text{Ø} 0.5 \text{ (M)} \end{matrix}$  Alle Loetkontakte  
ALL PINS

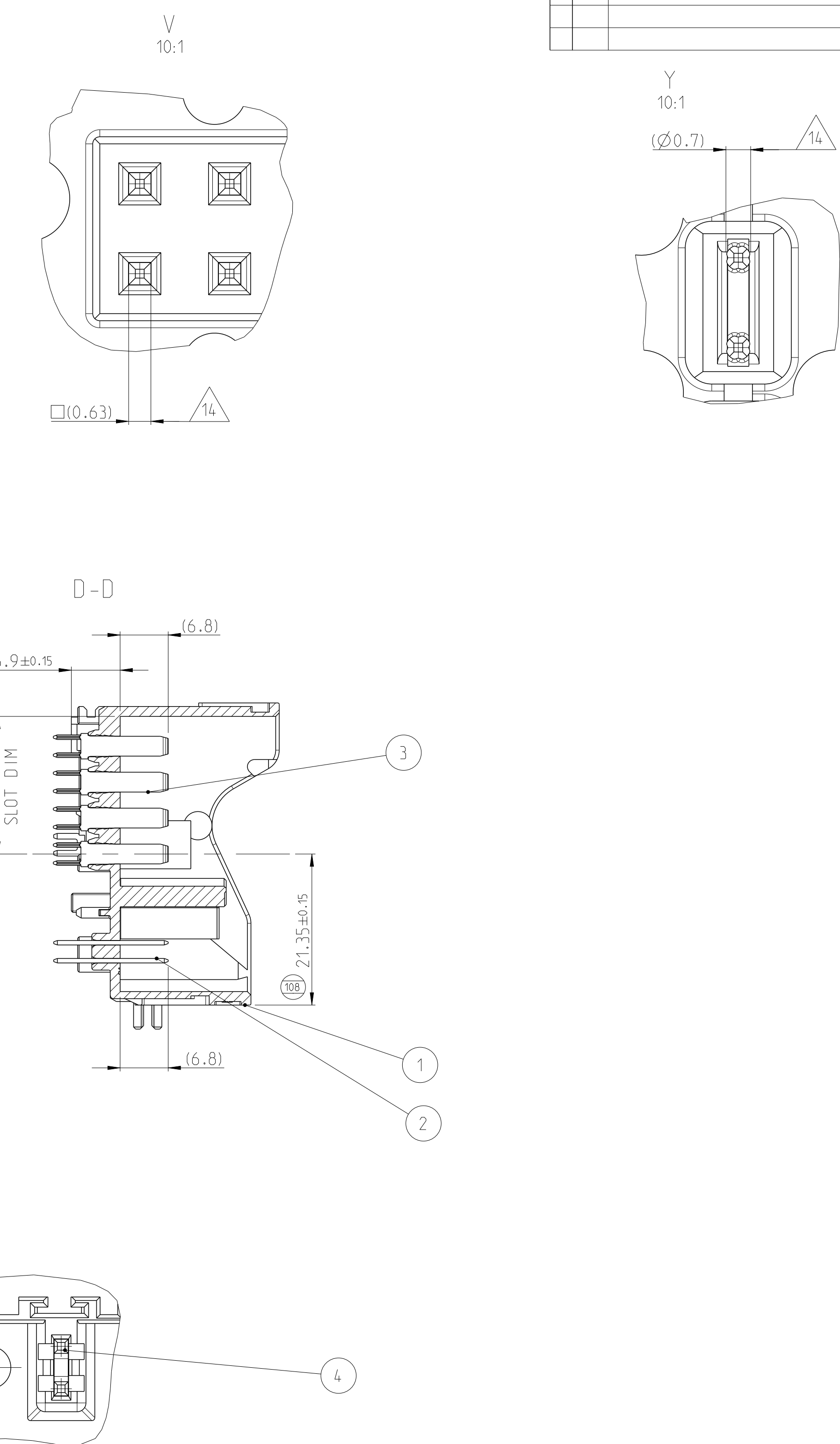
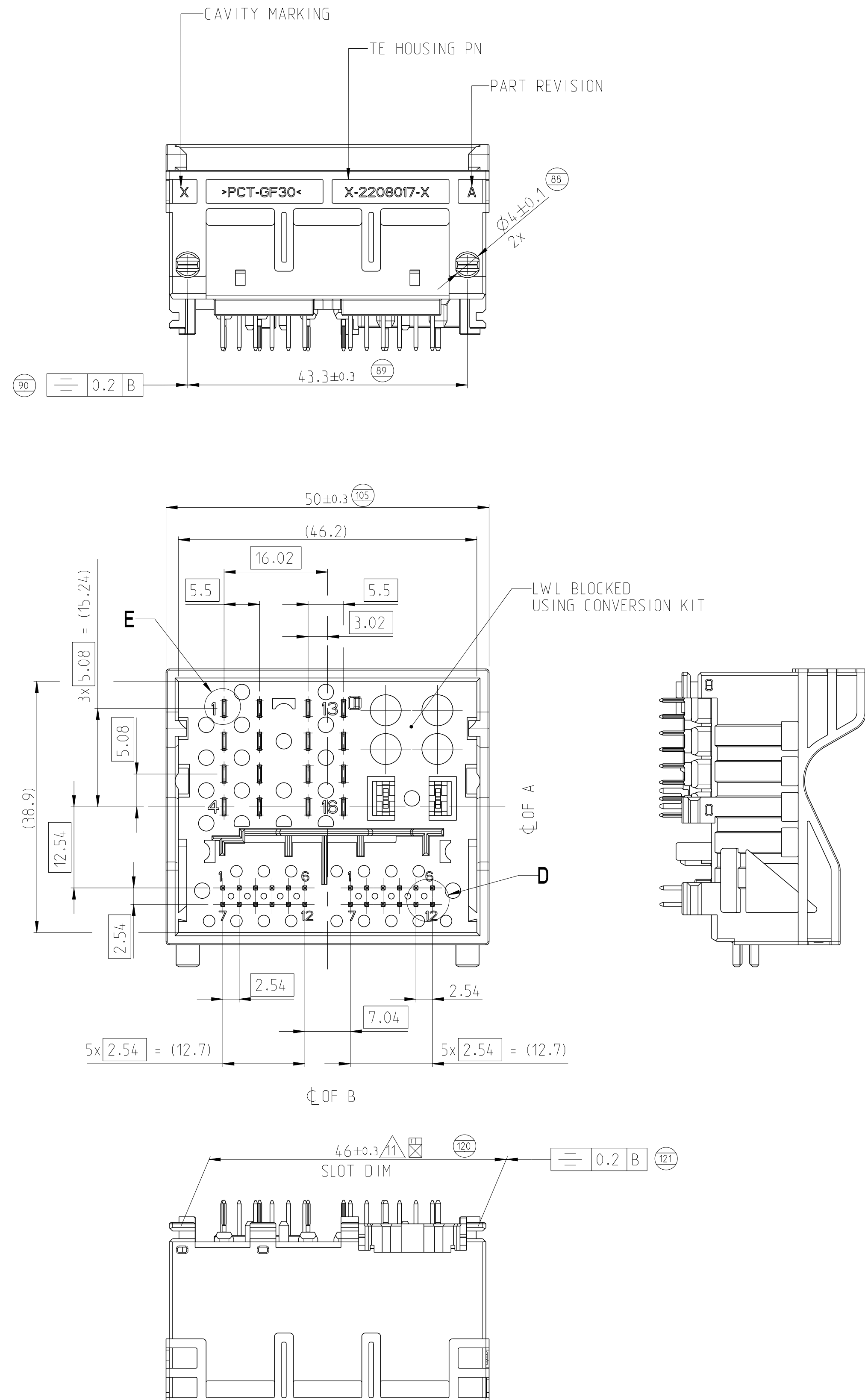
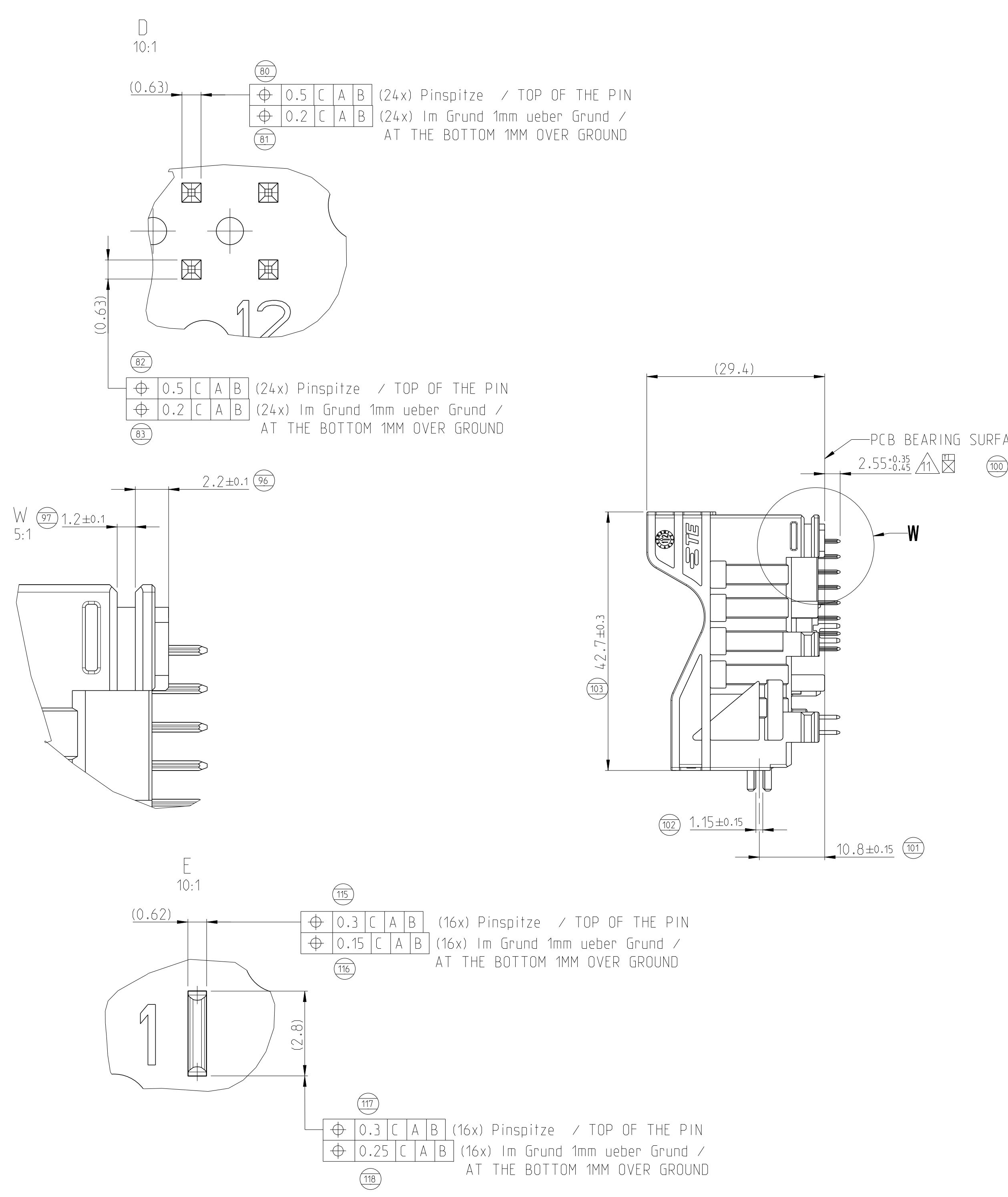
SHEET	ITEM	TE Bestell-Nr. ORDER NO.	VARIANTS	REV.	POS.	STK. QTY.	Benennung DESCRIPTION	MATERIAL	Bemerkungen NOTES	Oberflaeche SURFACE	Passend zu Buchsenhaeuse SUITABLE FOR SOCKET HOUSING
SHEET 2	ITEM 6	PRJ-15-3056-100 (PRELIMINARY)	40 POS HEADER, WITH LWL AND SHIELD, WITH FUSECONTACT	A	7	1	SHIELD	Kaltband 0.3 DIN EN 10139 0201 C590	5	Cu-Flash UNDER 3-5 µm Sn, MATTE	124 1765-2
					4	2	FUSE CONTACT	CuNiSi	3-5 µm Sn over min 1 µm Ni		
					3	16	TAB 2.8 X 0.6	CuSn0.15	10	TIN HOT DIPPED (0.8-1.5 µm) 4-10 µm Sn SOLDER SIDE	
					2	24	(□ 0.63) MQS PIN	CuFe2	10	1-3 µm Sn over 1.3-2.2 µm Ni	
SHEET 5	ITEM 5	0-2208788-1	52 POS. Header 2.8 TABS WITH ONE SOLDER PINS	C	5	2	TAB 4.8 X 0.8	CuSn0.15	10	TIN HOT DIPPED (0.8-1.5 µm) 4-10 µm Sn SOLDER SIDE	-
					3	14	TAB 2.8 X 0.6	CuSn0.15	10	TIN HOT DIPPED (0.8-1.5 µm) 4-10 µm Sn SOLDER SIDE	
					2	36	(□ 0.63) MQS PIN	CuFe2	10	1-3 µm Sn over 1.3-2.2 µm Ni	
					1	1	PIN HEADER HSG	6	schwarz / black		
SHEET 4	ITEM 4	5-2208016-1	52 POS. Header 2.8 TABS WITH TWO SOLDER PINS	C	5	2	TAB 4.8 X 0.8	CuSn0.15	10	TIN HOT DIPPED (0.8-1.5 µm) 4-10 µm Sn SOLDER SIDE	-
					3	14	TAB 2.8 X 0.6	CuSn0.15	10	TIN HOT DIPPED (0.8-1.5 µm) 4-10 µm Sn SOLDER SIDE	
					2	36	(□ 0.63) MQS PIN	CuFe2	10	1-3 µm Sn over 1.3-2.2 µm Ni	
					1	1	PIN HEADER HSG	6	schwarz / black		
SHEET 3	ITEM 3	0-2208016-4	40 POS HEADER, WITHOUT LWL AND SHIELD, WITH FUSECONTACT	A	4	2	FUSE CONTACT	CuNiSi	3-5 µm Sn over min 1 µm Ni	124 1765-2	
					3	16	TAB 2.8 X 0.6	CuSn0.15	10		TIN HOT DIPPED (0.8-1.5 µm) 4-10 µm Sn SOLDER SIDE
					2	24	(□ 0.63) MQS PIN	CuFe2	10		1-3 µm Sn over 1.3-2.2 µm Ni
					1	1	PIN HEADER HSG	6	schwarz / black		
SHEET 3	ITEM 2	0-2208016-3	40 POS HEADER, WITH LWL, WITHOUT SHIELD, WITHOUT FUSECONTACT	C	3	16	TAB 2.8 X 0.6	CuSn0.15	10	TIN HOT DIPPED (0.8-1.5 µm) 4-10 µm Sn SOLDER SIDE	124 1765-2
					2	24	(□ 0.63) MQS PIN	CuFe2	10	1-3 µm Sn over 1.3-2.2 µm Ni	
					1	1	PIN HEADER HSG	6	schwarz / black		
					7	1	SHIELD	Kaltband 0.3 DIN EN 10139 0201 C590	5	Cu-Flash UNDER 3-5 µm Sn, MATTE	
SHEET 2	ITEM 1	0-2208016-1 OBSOLETE	40 POS HEADER, WITH LWL AND SHIELD, WITHOUT FUSECONTACT	D	3	16	TAB 2.8 X 0.6	CuSn0.15	10	TIN HOT DIPPED (0.8-1.5 µm) 4-10 µm Sn SOLDER SIDE	124 1765-2
					2	24	(□ 0.63) MQS PIN	CuFe2	10	1-3 µm Sn over 1.3-2.2 µm Ni	
					1	1	PIN HEADER HSG	6	schwarz / black		
					1	1	PIN HEADER HSG	6	schwarz / black		



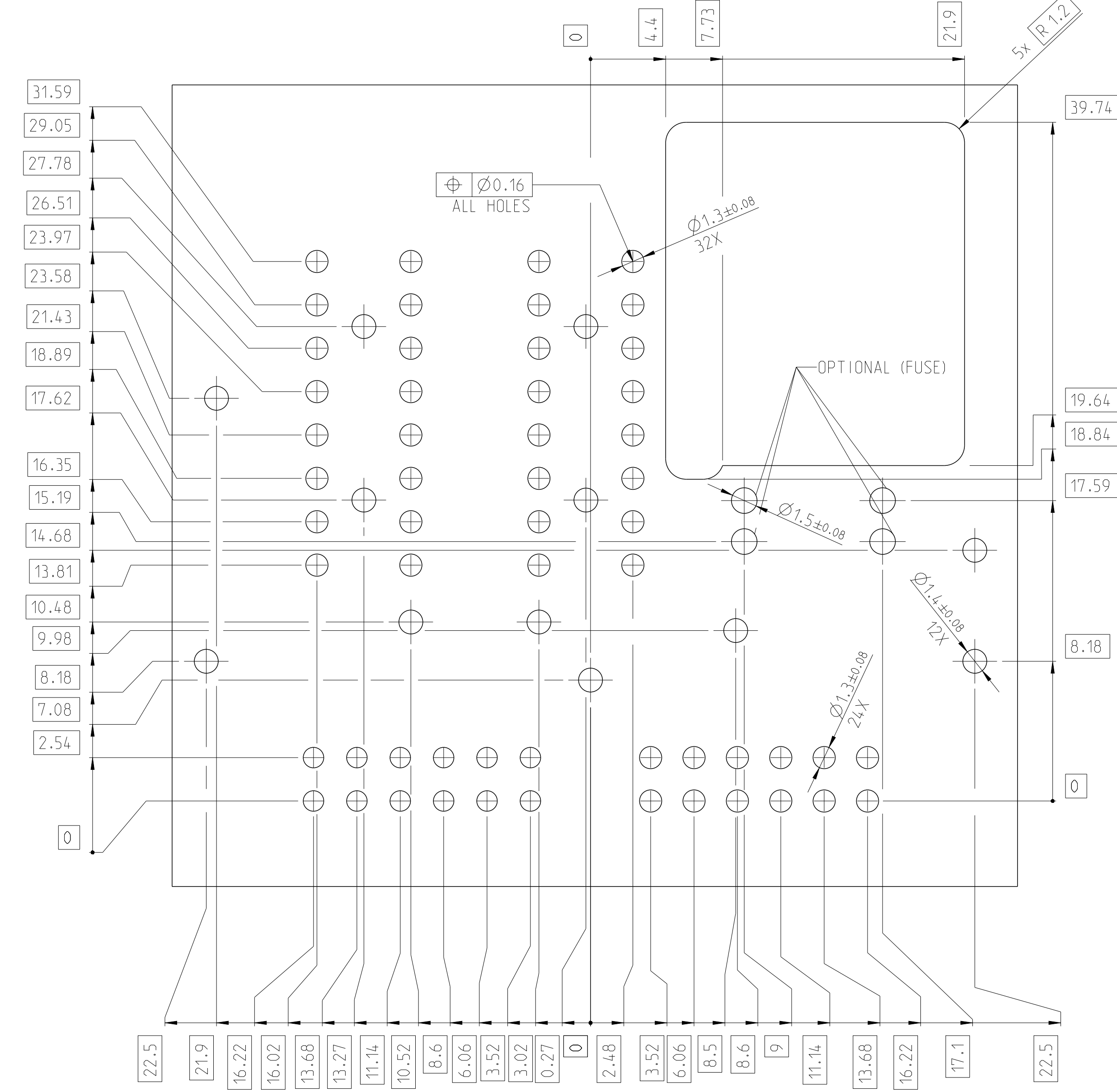


REVISIONS			
REV	DATE	BY	APPD
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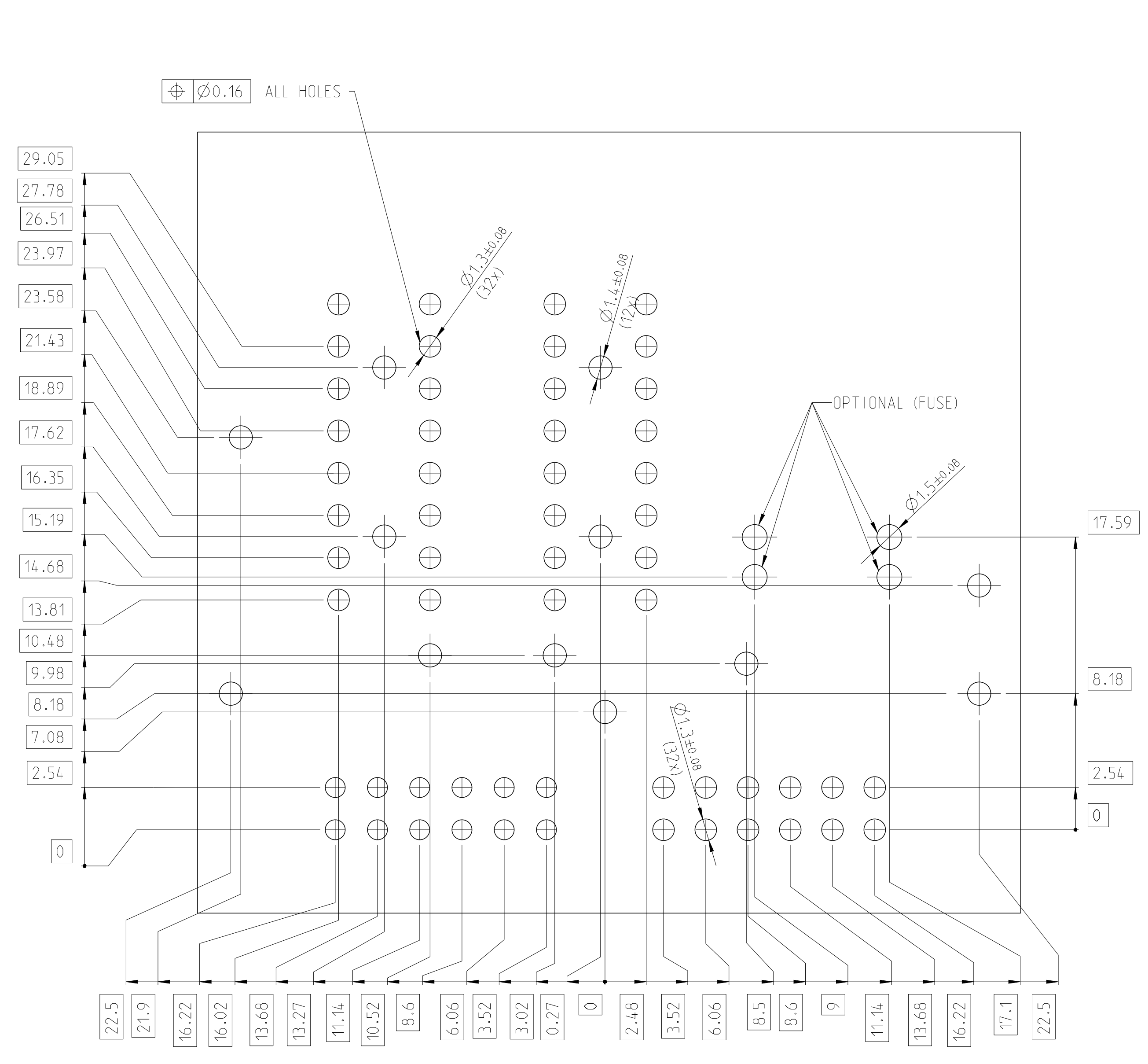
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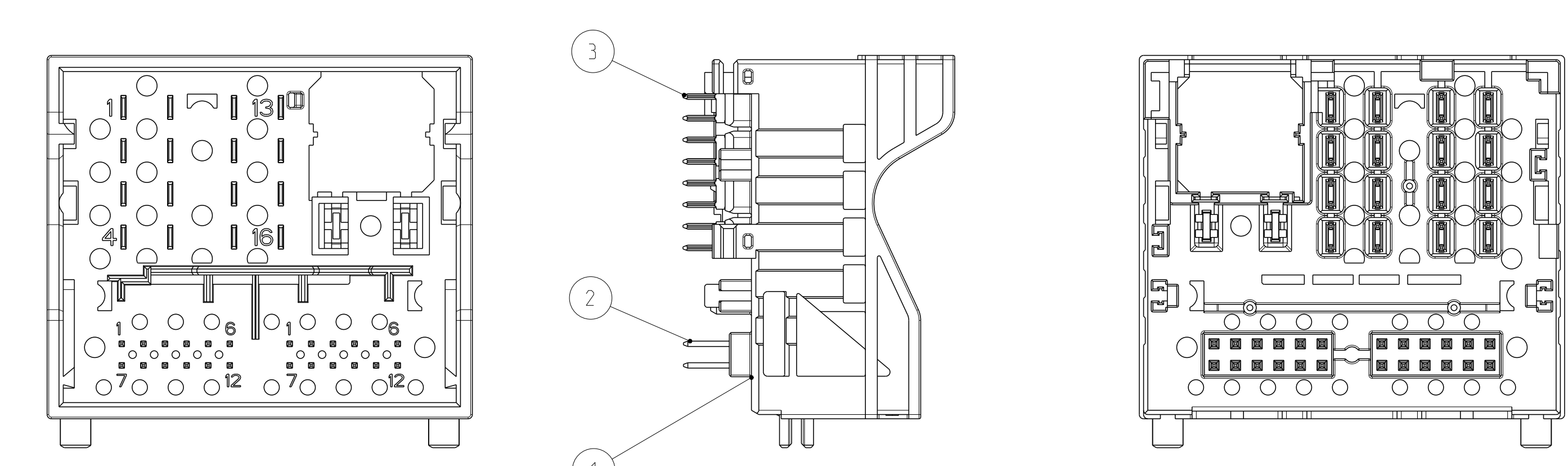
### Empfohlenes Lochbild fuer Leiterplatte (inklusive 7 Bohrungen fuer optionales Schirmblech) RECOMMENDED PCB LAYOUT FOR 0-2208016-2 (INCLUDING 7 HOLES FOR OPTIONAL SHIELD)



### Empfohlenes Lochbild fuer Leiterplatte (inklusive 7 Bohrungen fuer optionales Schirmblech) RECOMMENDED PCB LAYOUT FOR 0-2208016-4 (INCLUDING 7 HOLES FOR OPTIONAL SHIELD)

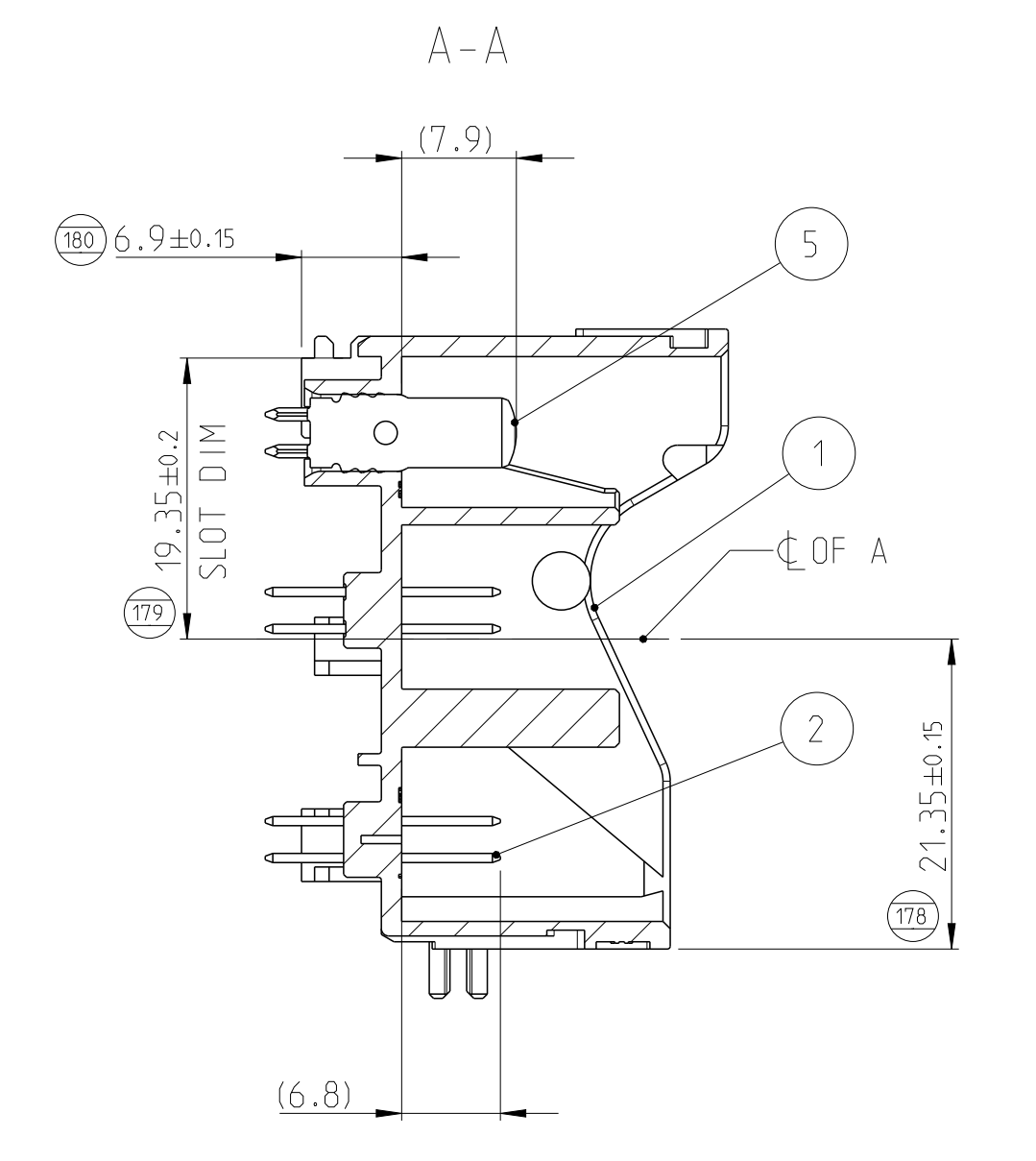
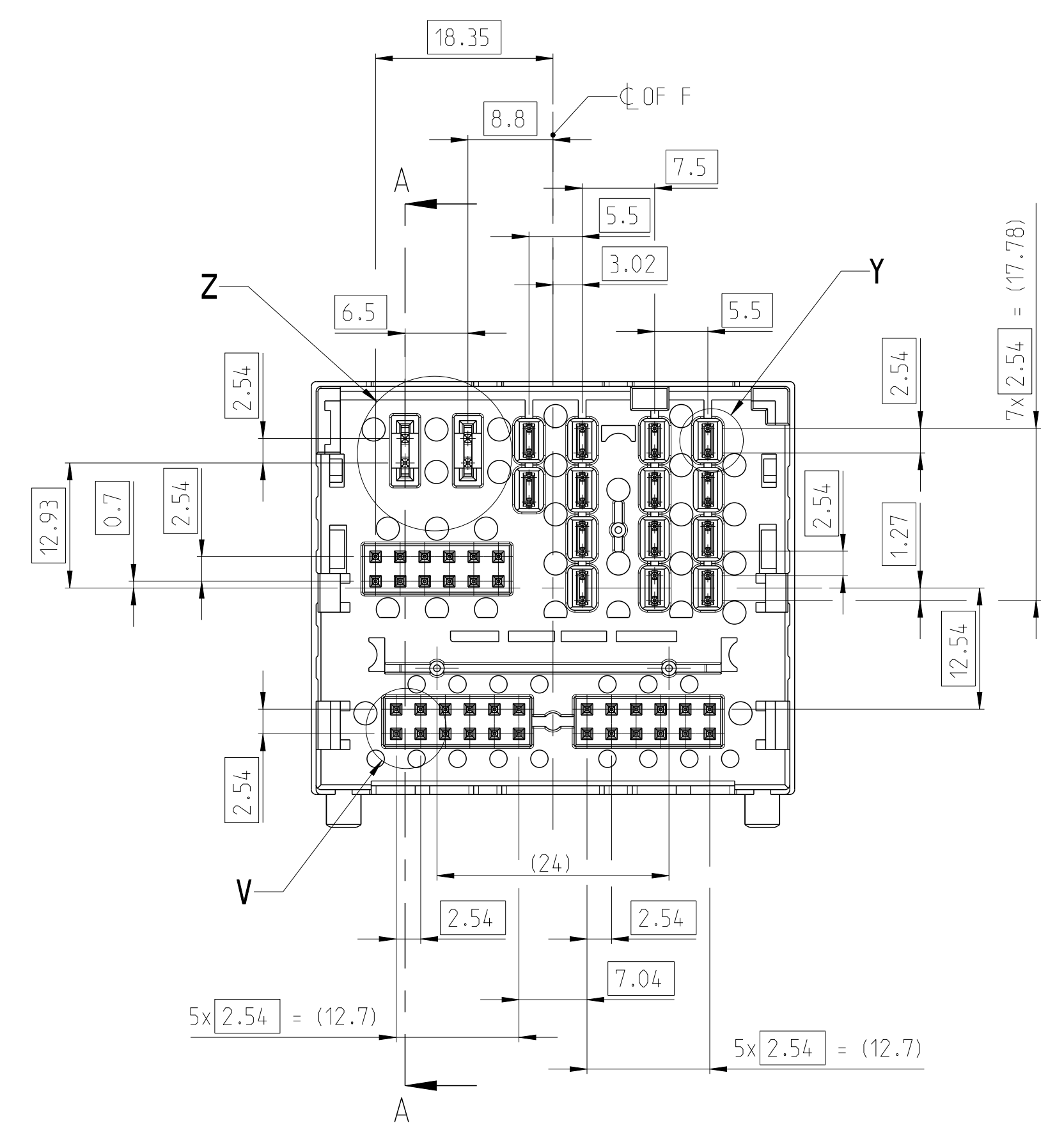
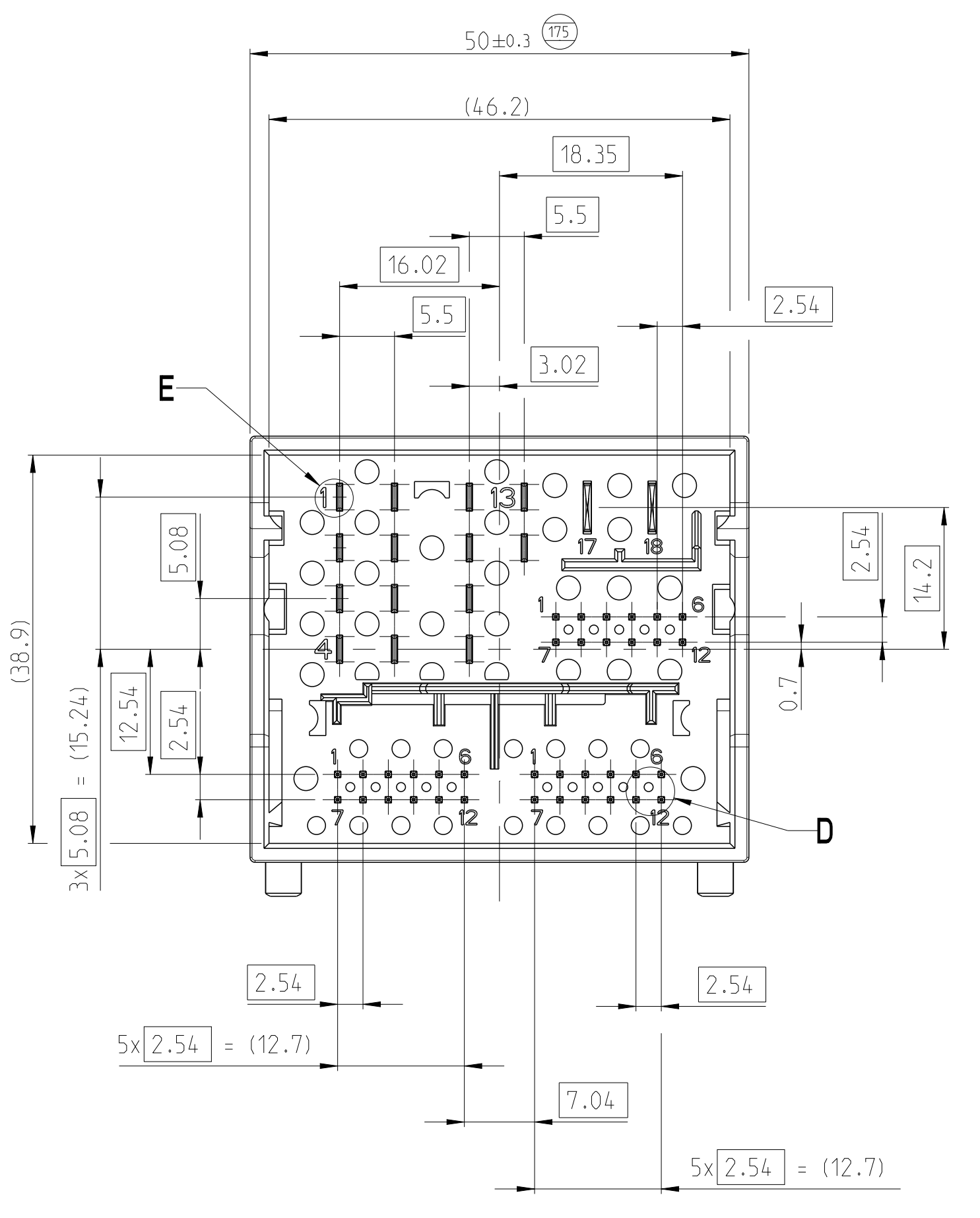
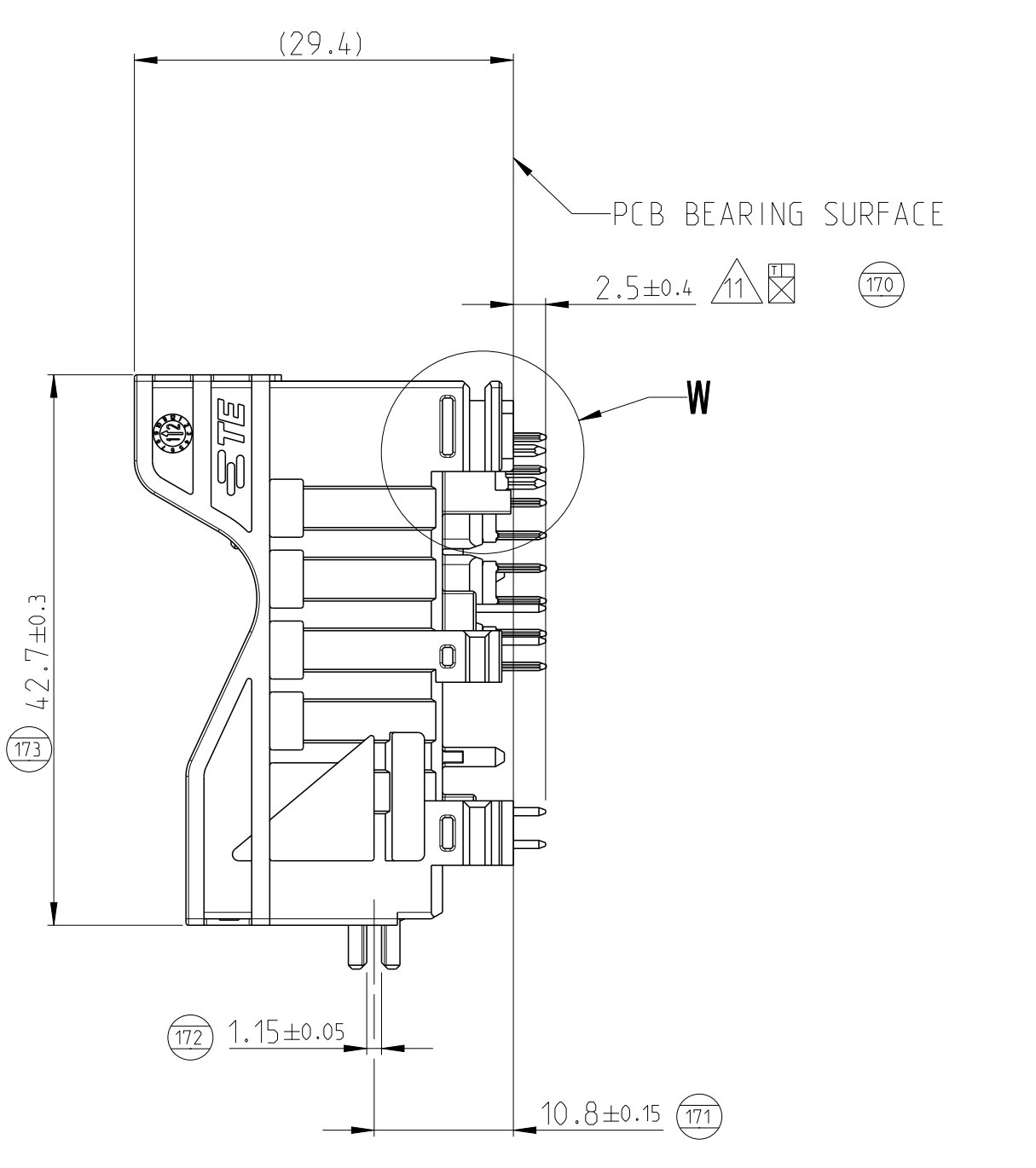
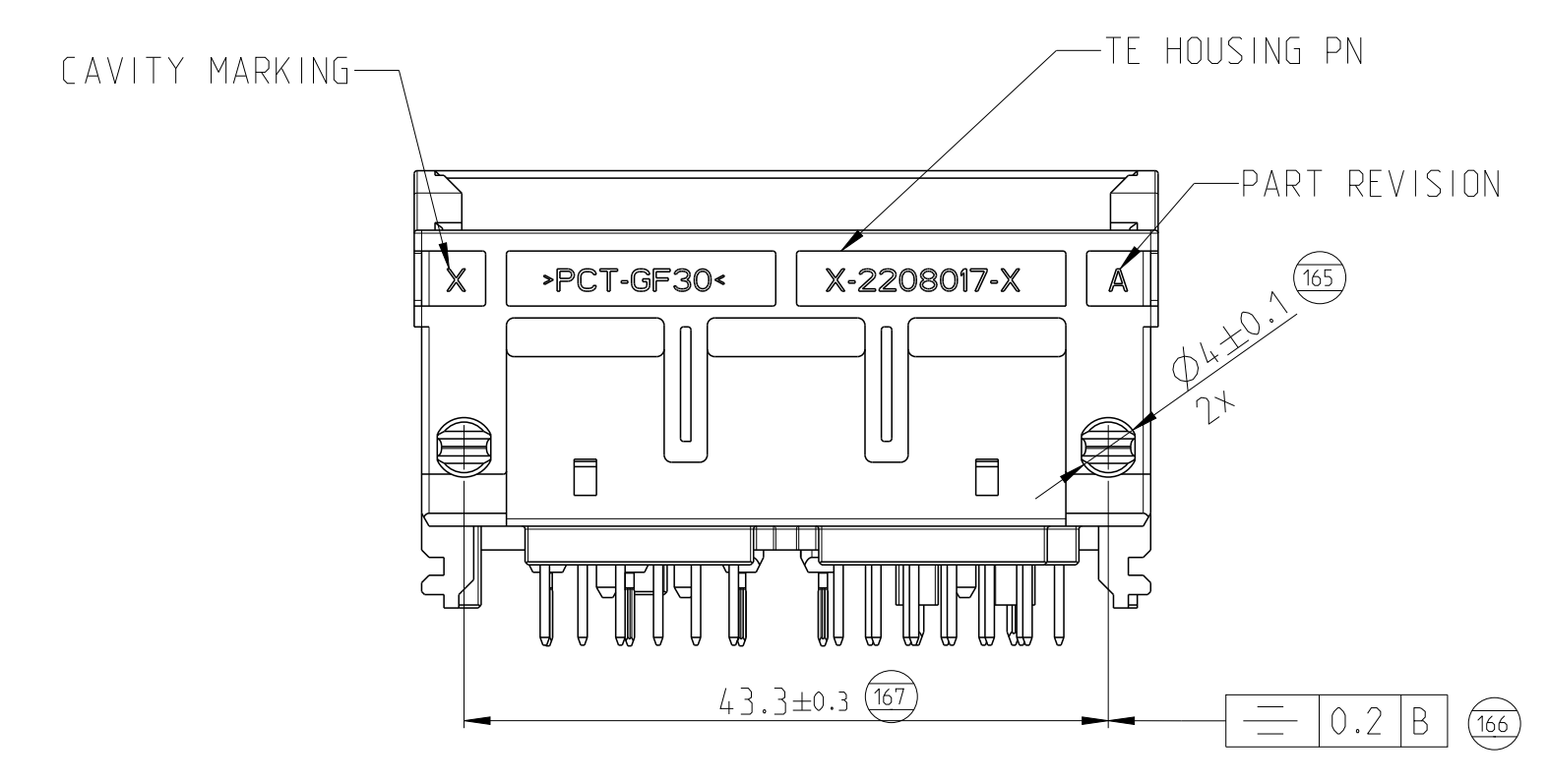
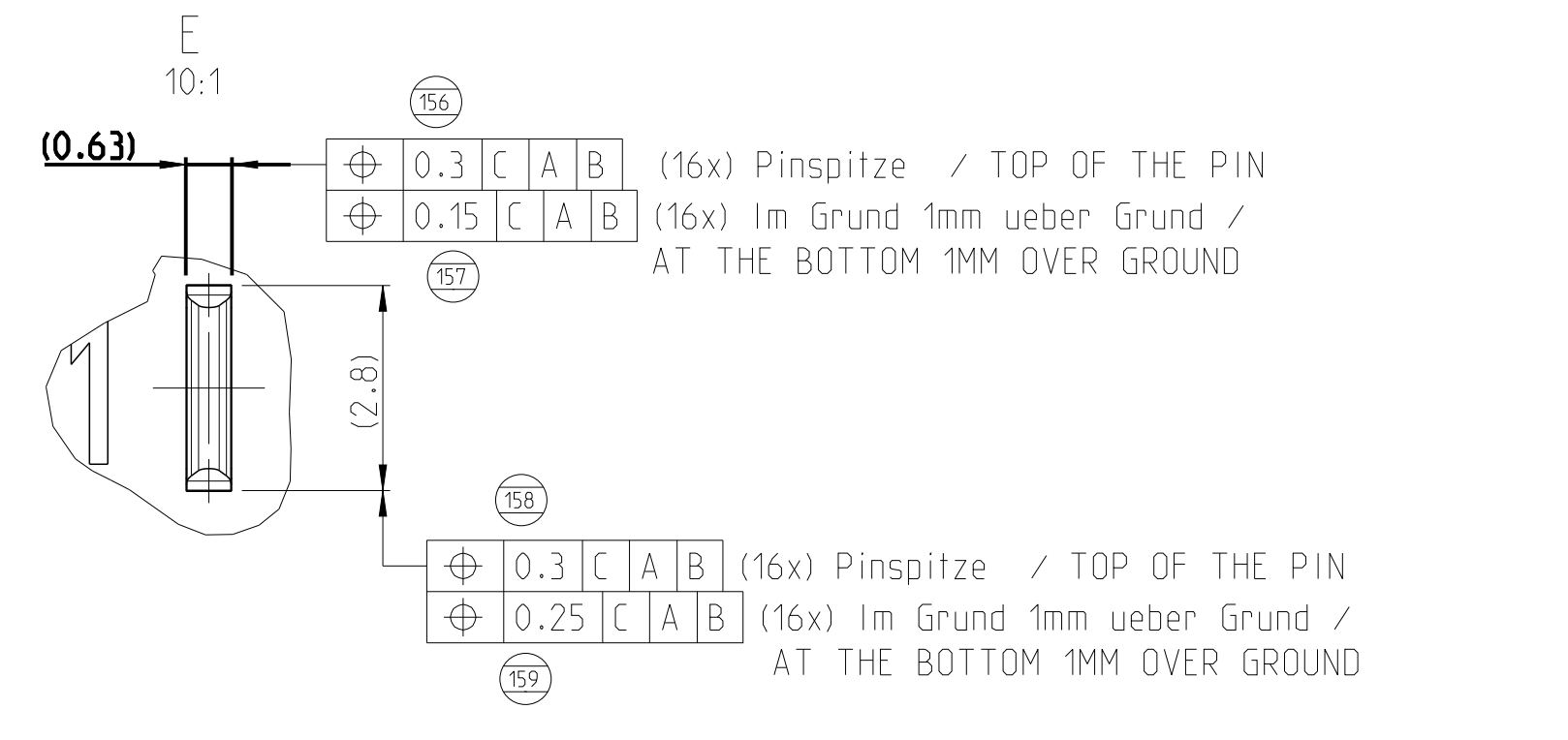
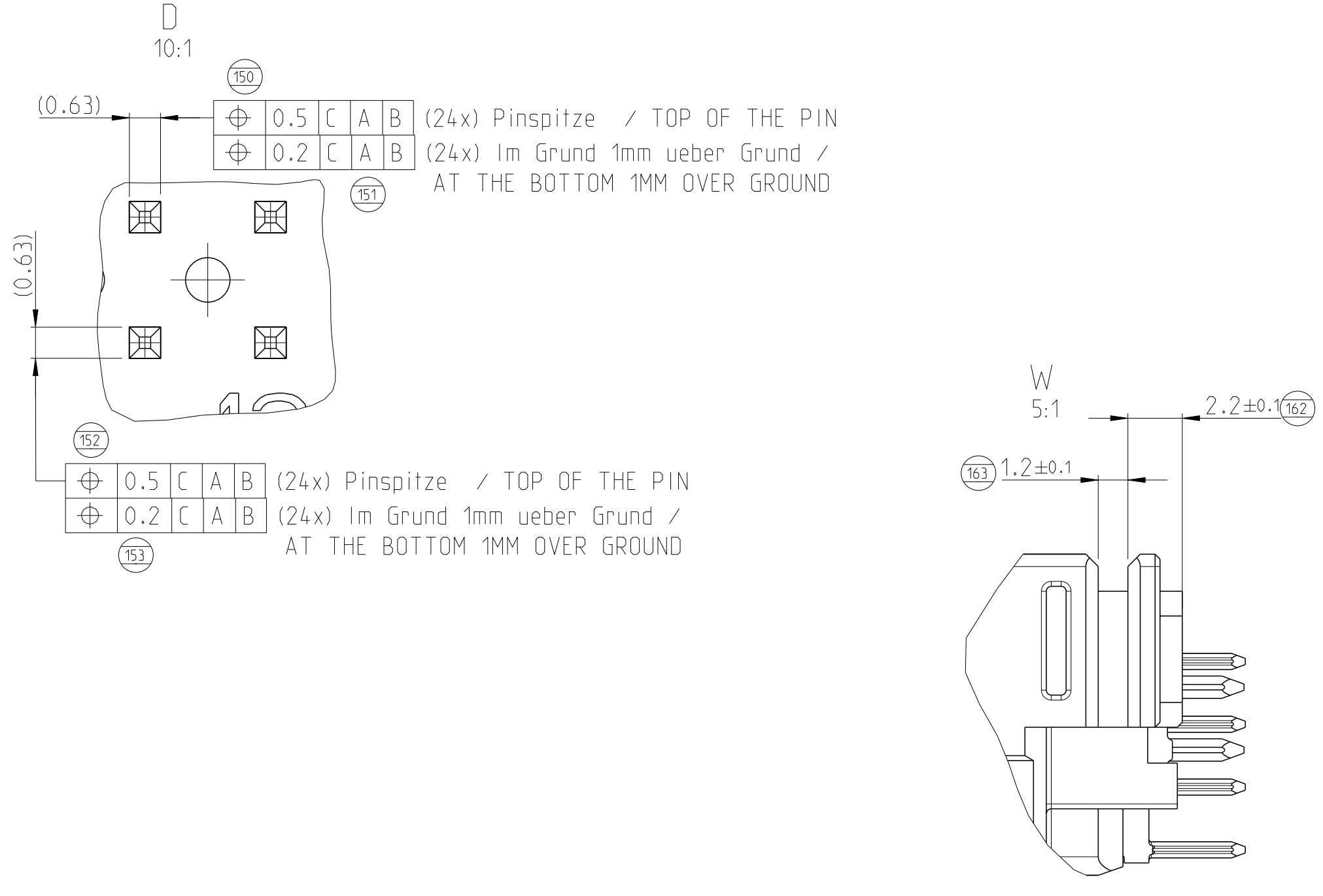


### AS SHOWN ITEM 2 Wie dargestellt ITEM 2 MISSING DIMENSIONS SEE ITEM 3 Fehlende Masse siehe Item 3

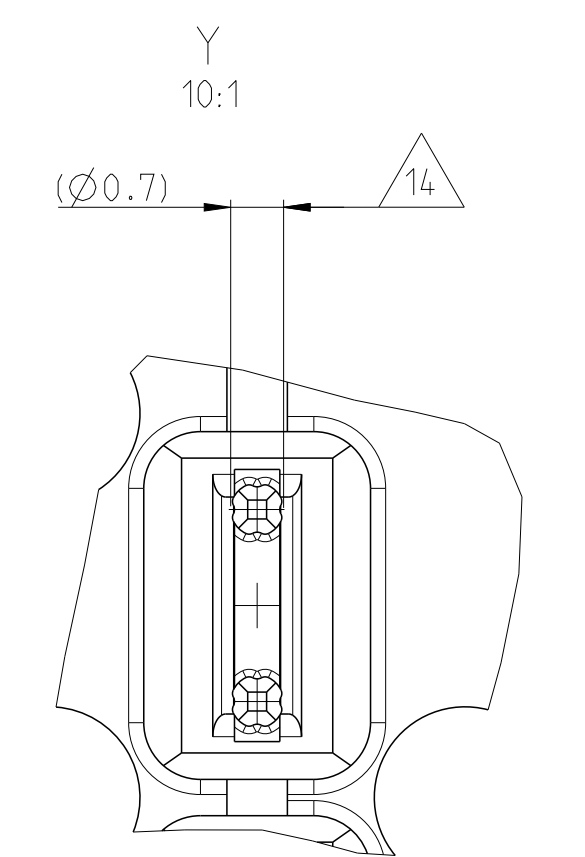
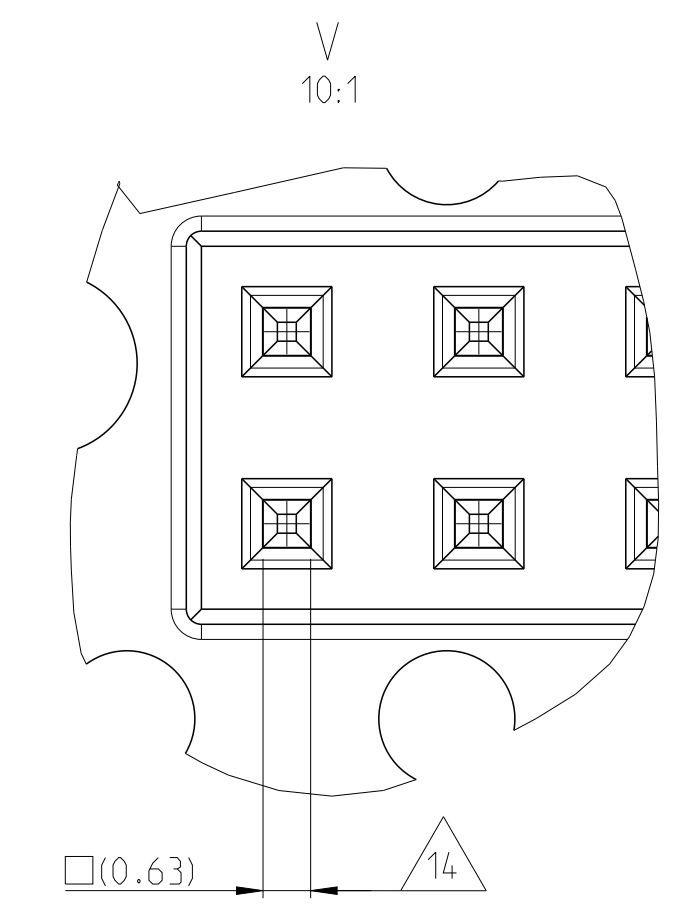
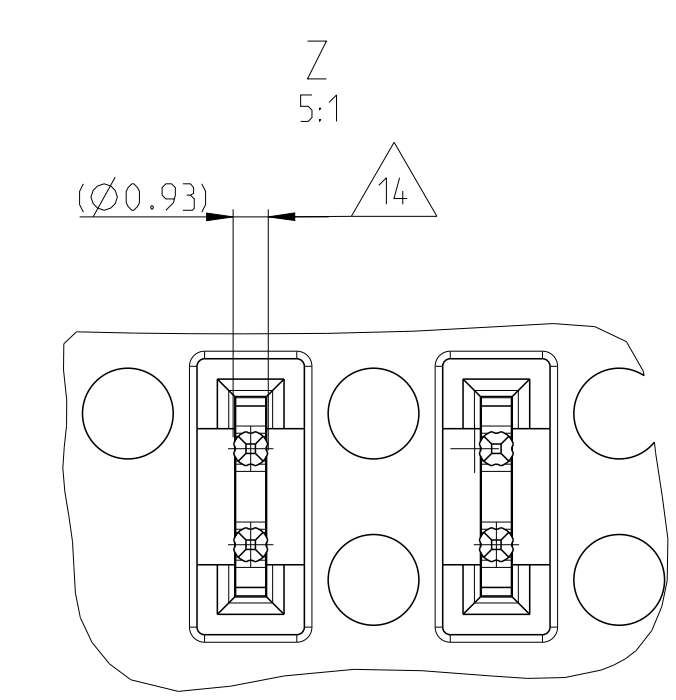
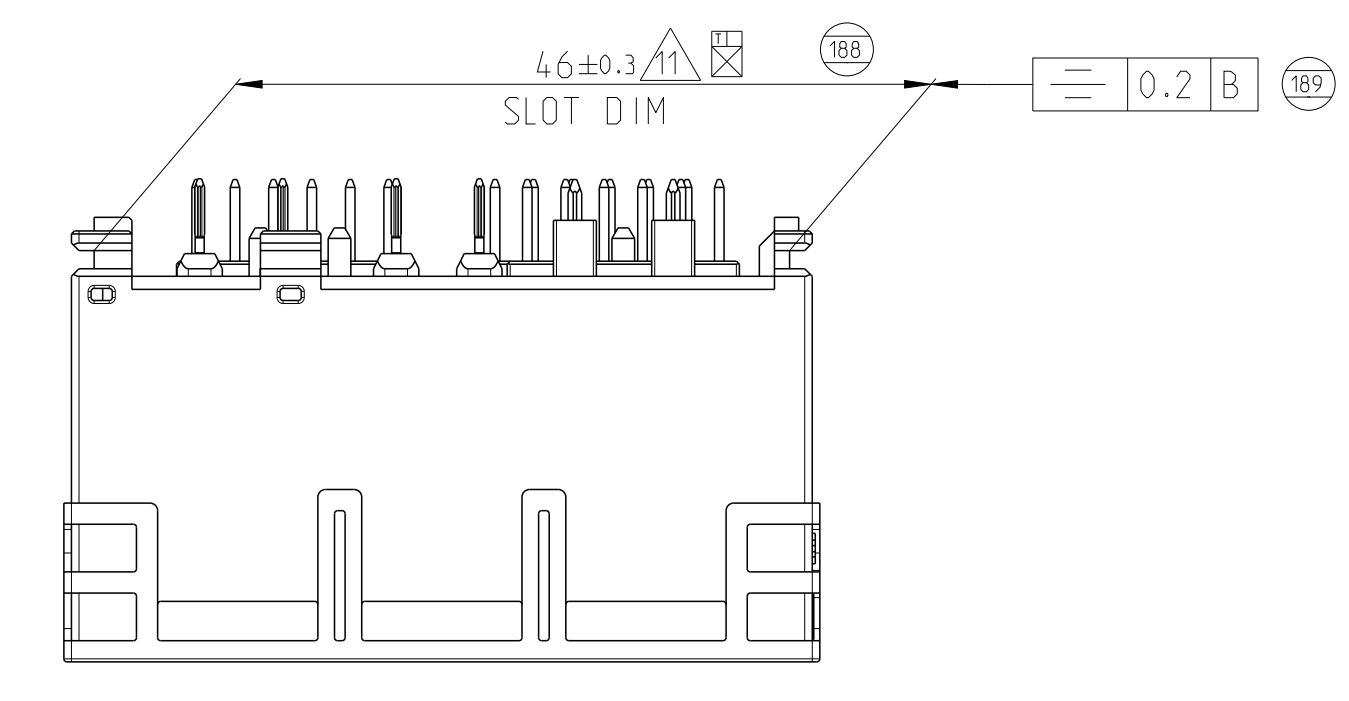
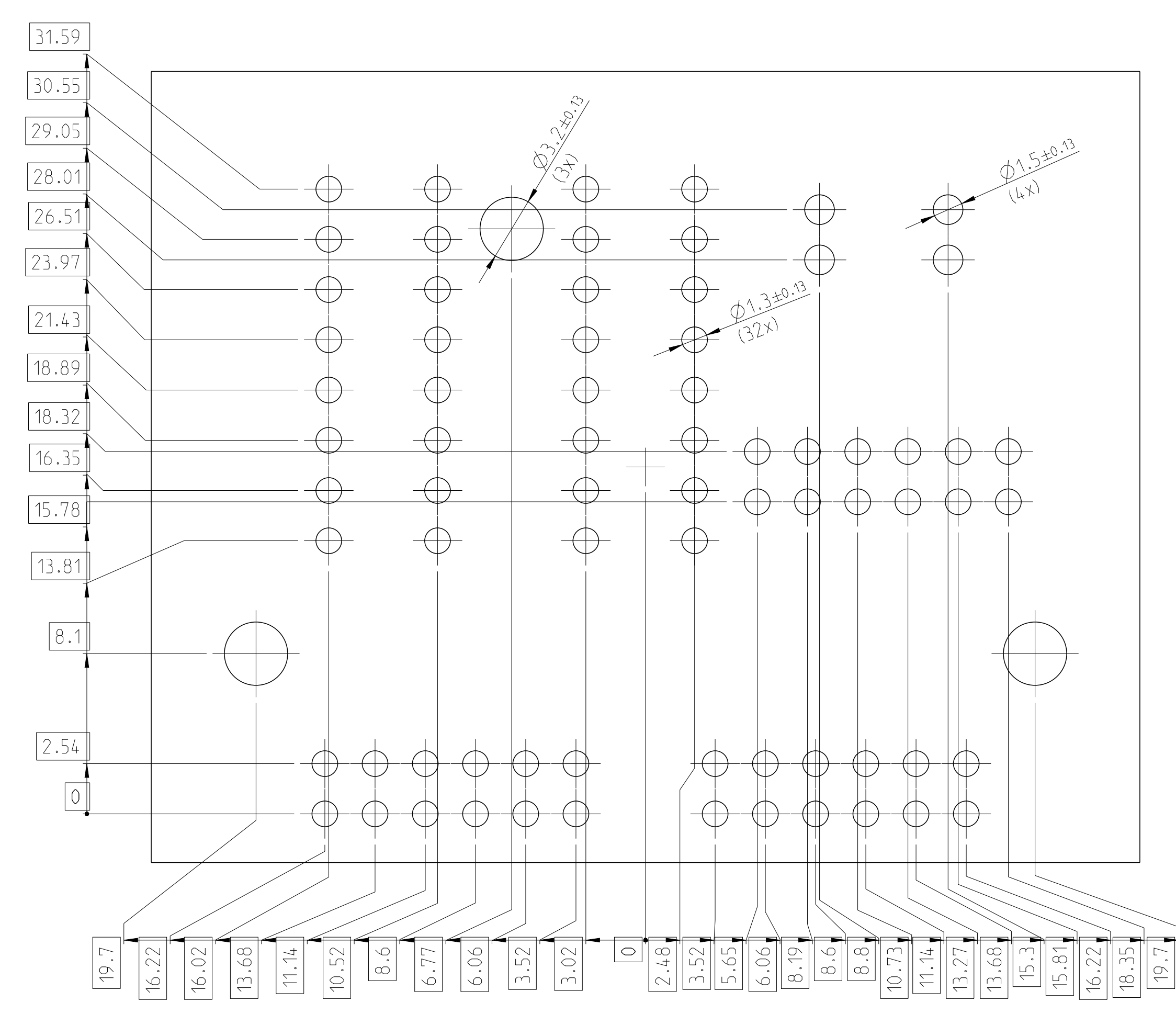


THIS DRAWING IS A CONTROLLED DOCUMENT.		DATE: 06 JUN 2012	BY: SANDEEP.HYDUR	REV: 1	APPD: K.T
DIMENSIONS: UNLESS OTHERWISE SPECIFIED.		DATE: 06 JUN 2012	BY: SANDEEP.HYDUR	REV: 1	APPD: K.T
MATERIAL: FINISH:		DATE: 06 JUN 2012	BY: SANDEEP.HYDUR	REV: 1	APPD: K.T
Customer Drawing		DATE: 06 JUN 2012	BY: SANDEEP.HYDUR	REV: 1	APPD: K.T
SCALE: 5:1		DATE: 06 JUN 2012	BY: SANDEEP.HYDUR	REV: 1	APPD: K.T
SHEET 3 OF 5		DATE: 06 JUN 2012	BY: SANDEEP.HYDUR	REV: 1	APPD: K.T

AS SHOWN ITEM 4  
 Wie dargestellt ITEM 4



Empfohlenes Lochbild fuer Leiterplatte  
 RECOMMENDED PCB LAYOUT FOR 48 AND 52 POS



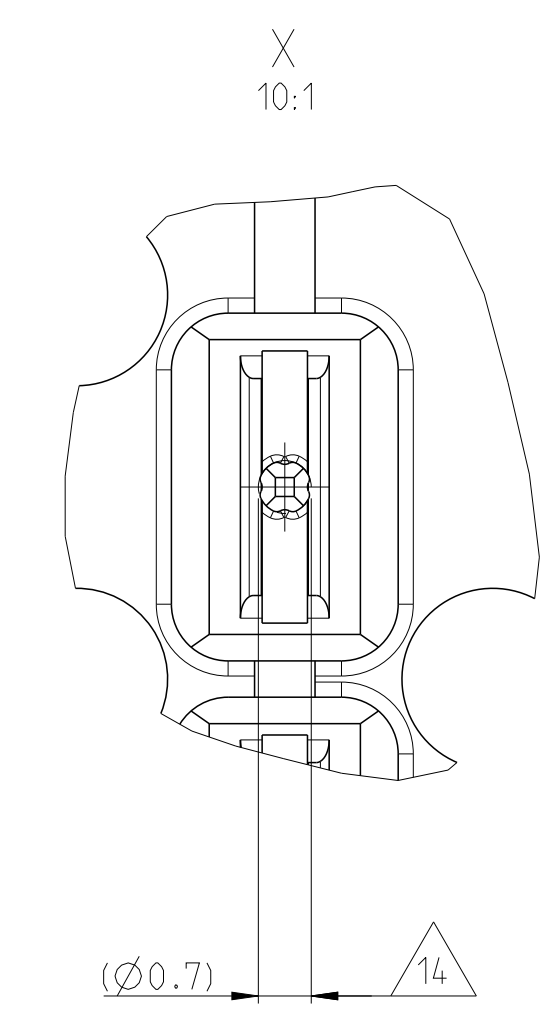
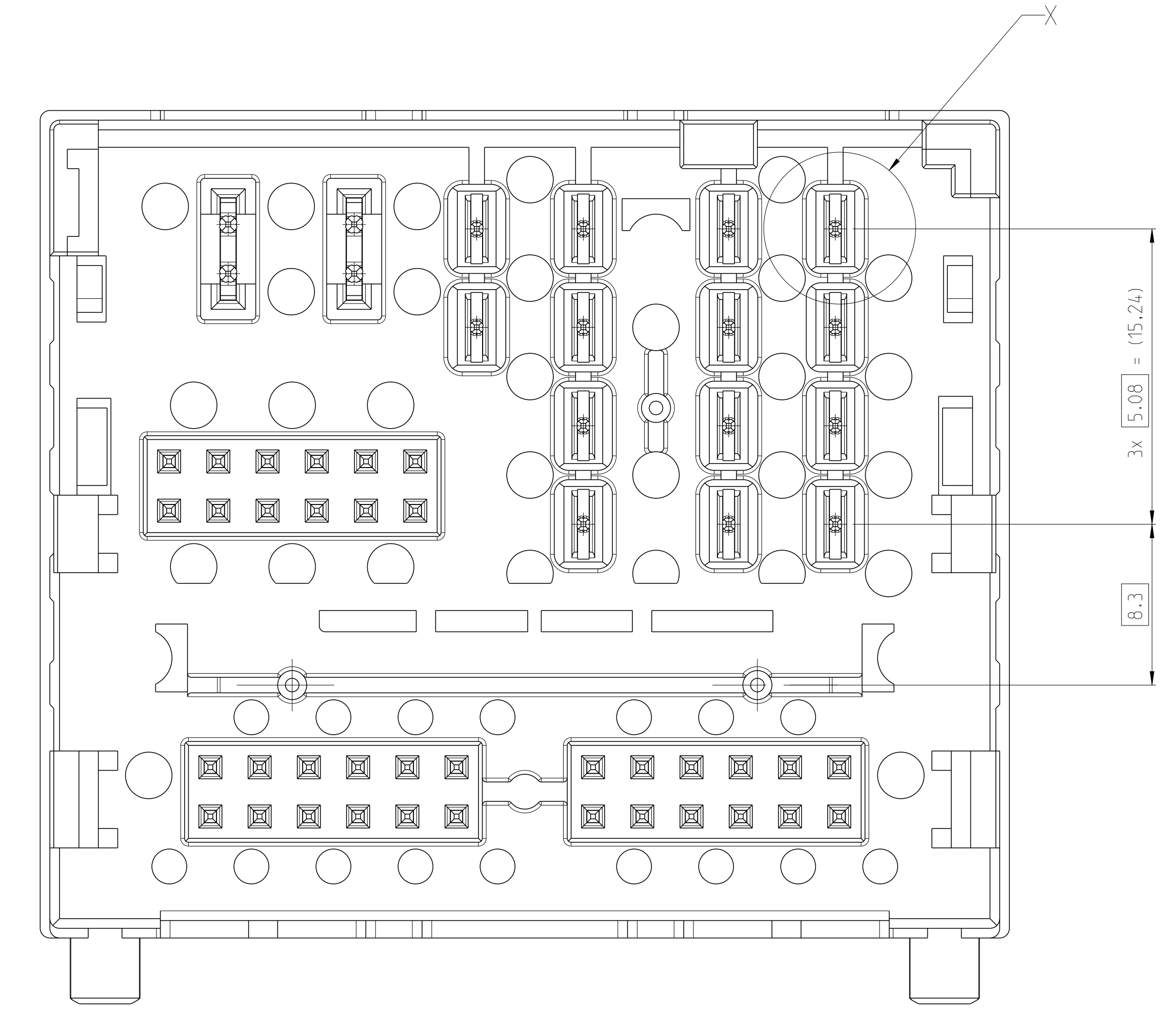
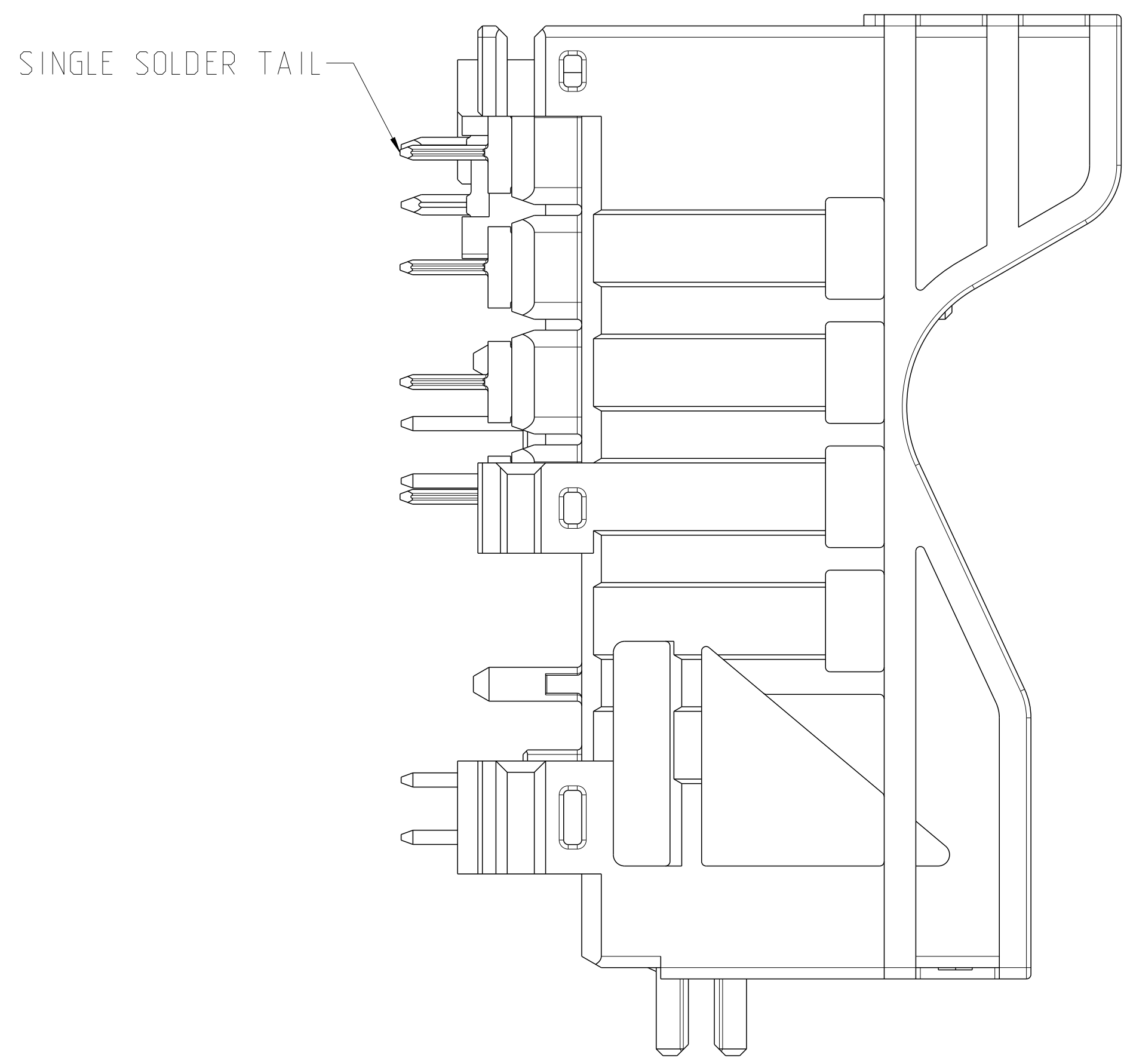
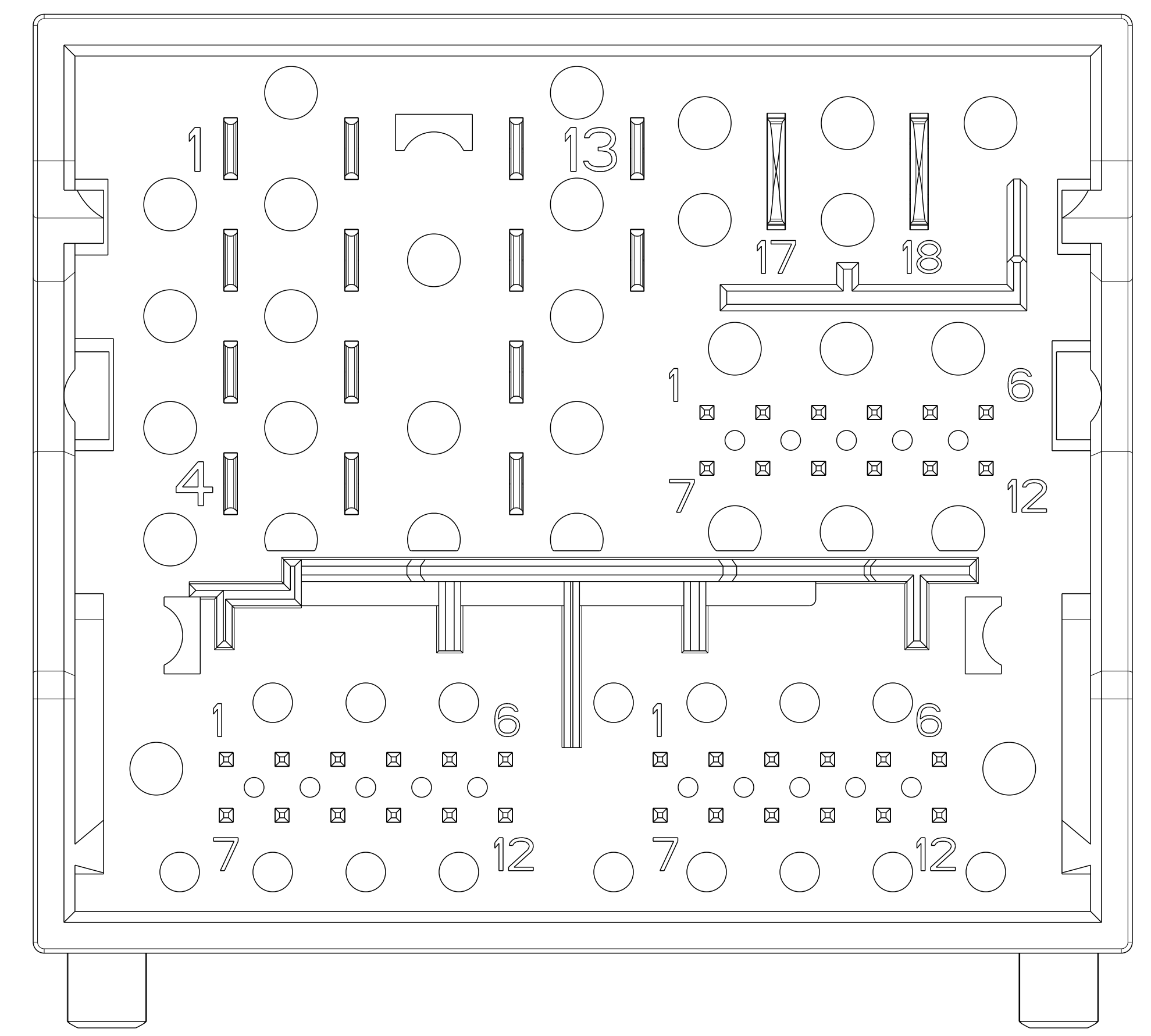
THIS DRAWING IS A CONTROLLED DOCUMENT. DAY: SANDEEP, 06 JUN 2012  
 CH: GOPI, K. T. 06 JUN 2012  
 APPROV: K. BECK, 06 JUN 2012

REV	DATE	DESCRIPTION	BY	APPD
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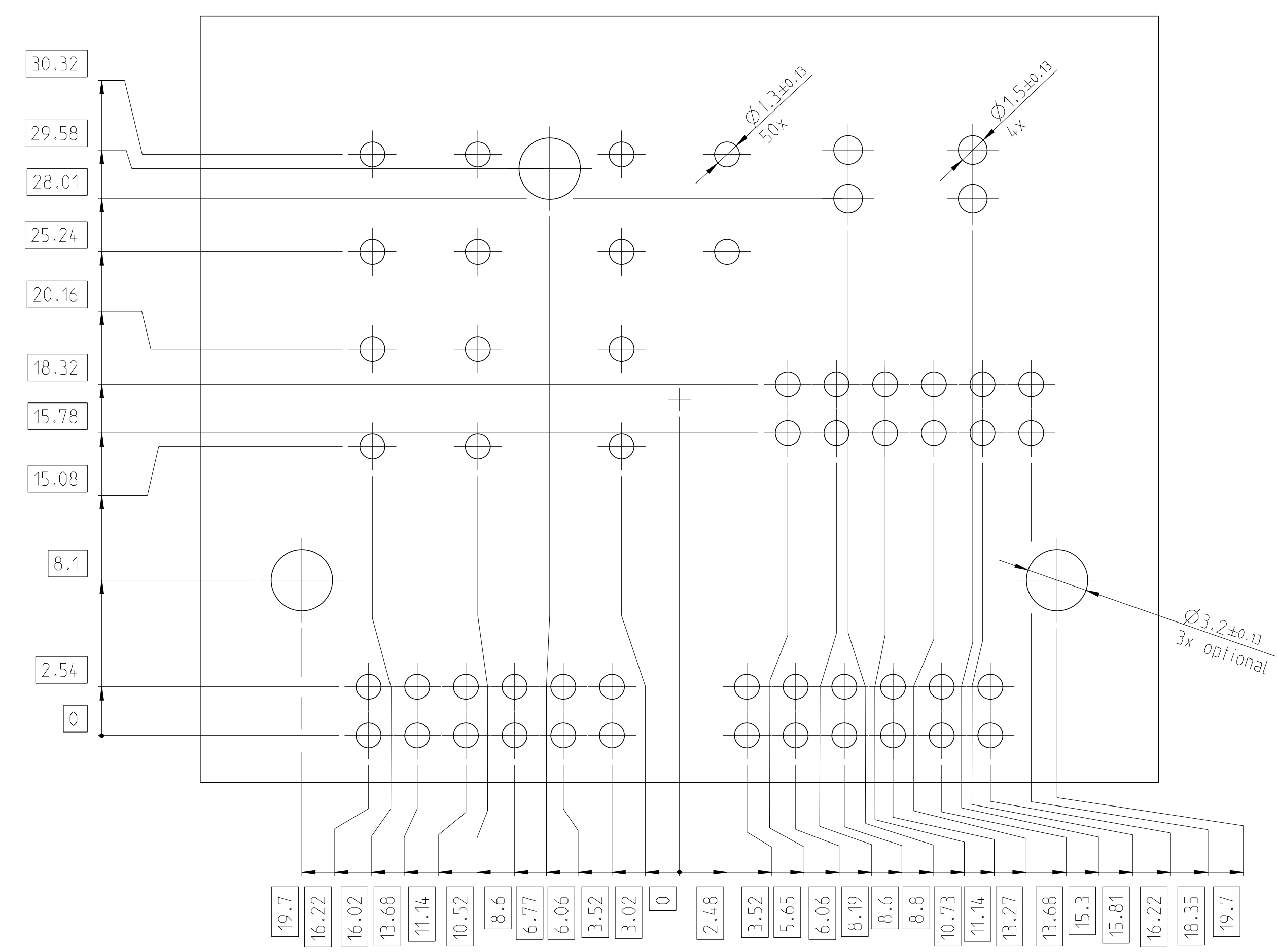
NAME: 40/52 POS MIXED HEADER ASSY  
 PRODUCT SPEC: -  
 APPLICATION SPEC: 114-94166  
 WEIGHT: -  
 MATERIAL: -  
 FINISH: -

Customer Drawing SCALE: 5:1 SHEET 6 of 5 REV: 02

AS SHOWN ITEM 5  
 Wie dargestellt ITEM 5  
 MISSING DIMENSIONS SEE ITEM 4  
 Fehlende Masse siehe Item 4



Empfohlenes Lochbild fuer Leiterplatte  
 RECOMMENDED PCB LAYOUT



THIS DRAWING IS A CONTROLLED DOCUMENT.		DATE: 06 JUN 2012	BY: SANDEEP.HYDUR	APPD: K.T.	NAME: 40/52 POS MIXED HEADER ASSY
DIMENSIONS: MILLIMETERS		DATE: 06 JUN 2012	CHK: GOPI.K.T.	APPD: K.BECK	NAME: 40/52 POS MIXED HEADER ASSY
OTHERWISE SPECIFIED:		DATE: 06 JUN 2012	CHK: K.BECK	APPD: K.BECK	NAME: 40/52 POS MIXED HEADER ASSY
MATERIAL:		DATE: 06 JUN 2012	CHK: K.BECK	APPD: K.BECK	NAME: 40/52 POS MIXED HEADER ASSY
FINISH:		DATE: 06 JUN 2012	CHK: K.BECK	APPD: K.BECK	NAME: 40/52 POS MIXED HEADER ASSY
Customer Drawing		SCALE: 5:1	SHEET: 5 of 5	REV: 02	RESTRICTED TO